# FS04\_PB

# High-voltage safety PMIC with SMPS and LDO Rev. 1.1 — 4 September 2024

**Product brief** 



#### **Document information**

| Information | Content  |
|-------------|--|
| Keywords    | FS04, PMIC, central compute, ASIL D, gateway, in-vehicle network, domain controller, telematics  |
| Abstract    | The FS04 is an automotive multi-output power management IC that focuses on central compute, gateway, in-vehicle network, and domain controller applications. The device includes a high-voltage buck converter, multiple high-efficiency switch modes and linear voltage regulators. |



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### 1 Overview

The FS04 is an automotive multi-output power management IC that focuses on central vehicle controller, gateway, in-vehicle network, and domain controller applications. The device includes a high-voltage buck converter, multiple high-efficiency switch modes and linear voltage regulators.

The FS04 includes enhanced safety features with fail-safe outputs and dedicated safety pins for the processor S32N. The device covers ASIL B and ASIL D safety integrity levels. It complies with the ISO 26262 standard and is qualified in accordance with AEC-Q100 rev H (Grade1, MSL3). The FS04 can be fully utilized in safety-oriented system partitioning and can also be configured to operate as a non-safety QM-version part.

The FS04 is available in several versions that support a variety of safety applications and offer numerous choices with respect to the number of output rails, output voltage settings, operating frequencies, and power-up sequencing.

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### 2 Features

- A high-voltage synchronous buck controller, driving external MOSFETs:
  - Input voltage, 3 V to 60 V
  - Output voltage from 3.3 V to 5.3 V
  - Up to 1.5% DC accuracy in pulse width modulation (PWM) mode and 3% DC accuracy in pulse frequency modulation (PFM) mode
  - 50 mA gate drive capability, up to 20 A DC output current capability
  - Switching frequencies 312 kHz to 455 kHz
- · Five buck regulators with internal power stage
  - BUCK1 single-phase operation, 1 V to 1.8 V @ 2.5 A DC with up to 1.0 % DC accuracy
  - BUCK2 single-phase operation, 1 V to 1.8 V @ 2.5 A DC with up to 1.0 % DC accuracy
  - BUCK3 single-phase operation, 0.4 V to 1.8 V @ 2.5 A DC with up to 1.0 % DC accuracy
  - BUCK4 single-phase operation, 0.4 V to 1.8 V @ 2.5 A DC with up to 1.0 % DC accuracy
  - BUCK5 / switch mode, 0.6 V to 1.8 V @ 70 mA in buck mode and 150 mA in switch mode
- One low-power linear regulator
  - LDO1: LDO/load Switch with output voltage from 1.1 V to 3.3 V @ 400 mA DC
- · One boost regulator with integrated low-side switch
  - Output voltage, 4.5 V to 5.5 V @ 1 A DC with up to 2.0 % DC accuracy
- Advanced frequency management, including frequency spread spectrum, slew rate control, manual frequency tuning.
- Functional safety architecture to target ASIL D applications.
- · ABIST and LBIST for latent fault detection
- · Optimized low-power architecture
- High-speed I<sup>2</sup>C interface with up to 3.4 MHz operation
- · Advanced thermal monitoring and thermal shutdown protection
- 64-pin QFN package with exposed pad and 0.5 mm pitch
- · Automotive qualified AEC-Q100 up to Grade 1

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### 3 Applications

- · Central vehicle controller
- Gateway
- In-vehicle networks
- Domain controllers

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### 4 Ordering information

#### Table 1. Ordering information

| Туре   | Package |   |              |  |  |
|--------|---------|---|--------------|--|--|
| number | Name    | Description   | Version      |  |  |
| FS0400 | QFN64   | QFN64 package with exposed pad, thermally enhanced wettable flanks, 64 terminals, 0.5mm pitch, 9 mm x 9 mm. | SOT804-8(DD) |  |  |

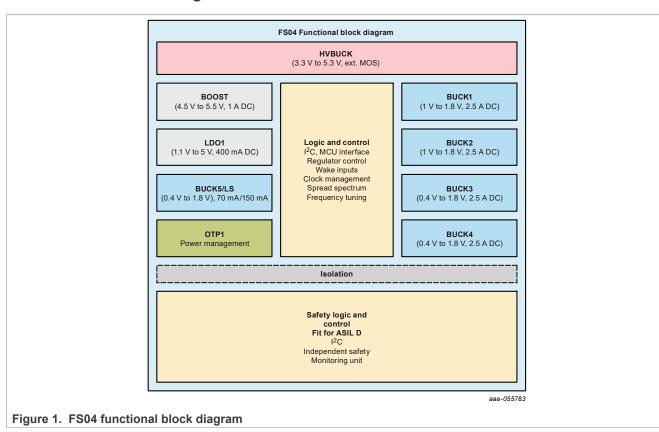
### Table 2. Ordering part number and OTP version

| Part number    | NXP processor | Safety grade | OTP ID |
|----------------|---------------|--------------|--------|
| PFS0400AMDA3ES | S32N          | ASIL D       | DA3    |

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### 5 Device description

### 5.1 Functional block diagram



### 5.2 Power rail summary

#### Table 3. Voltage regulator summary

| Regulator | Туре  | Input Supply   | Output Range   | Output current    |
|-----------|---|----------------|----------------|-------------------|
| HVBUCK    | High-voltage buck controller                      | 2.7 V to 60 V  | 3.3 V to 5.3 V | 20 A DC           |
| BUCK1     | Single-phase buck regulator                       | 2.5 V to 5.5 V | 1 V to 1.8 V   | 2.5 A DC          |
| BUCK2     | Single-phase buck regulator                       | 2.5 V to 5.5 V | 1 V to 1.8 V   | 2.5 A DC          |
| BUCK3     | Single-phase buck regulator                       | 2.5 V to 5.5 V | 0.4 V to 1.8 V | 2.5 A DC          |
| BUCK4     | Single-phase buck regulator                       | 2.5 V to 5.5 V | 0.4 V to 1.8 V | 2.5 A DC          |
| BUCK5     | Single-phase buck regulator with load switch mode | 0.6 V to 5.5 V | 0.6 V to 1.8 V | 70 mA / 150 mA DC |
| LDO1      | LDO with load switch                              | 2.5 V to 5.5 V | 1.1 V to 3.3 V | 400 mA DC         |
| BOOST     | Boost regulator                                   | 2.7 V to 6 V   | 4.5 V to 5.5 V | 1 A DC            |

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### 5.3 Thermal characteristics

Table 4. Thermal characteristics

| Symbol          | Description  | Min | Тур | Max | Units |
|-----------------|--|-----|-----|-----|-------|
| T <sub>A</sub>  | Ambient operating temperature • Grade 1 <sup>[1]</sup> | -40 |     | 125 | °C    |
| T <sub>J</sub>  | Junction temperature                                   | -40 |     | 150 | °C    |
| T <sub>ST</sub> | Storage temperature range                              | -55 |     | 150 | °C    |

<sup>[1]</sup> Maximum T<sub>A</sub> will depend on the overall power dissipated on the device.

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### **Revision history**

#### Table 5. Revision history

| Document ID   | Release date | Description  |
|---------------|--------------|--|
| FS04_PB v1.1  | 4 Sept 2024  | <ul> <li><u>Section 2</u>: corrected definitions of PWM and PFM abbreviations</li> <li><u>Section 5.2</u>: inserted with load switch mode in BUCK5 type column</li> <li>Updated legal information</li> </ul> |
| FS04_PB v.1.0 | 11 June 2024 | Initial version  |

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